WHAT IS CLAIMED IS:

1. A method for assembling an integral type electronic component, which comprises:

storing and holding an electronic component to a component storage part of a first board; and

electrically connecting a second board to the electronic component held to the first board, thereby forming the integral type electronic component of the first board and the second board.

2. The method for assembling the integral type electronic component according to claim 1, wherein bumps of the second board are flattened before the second board is electrically connected to the electronic component after the electronic component is held to the first board.

3. An integral type electronic component which comprises:

a first board with a component storage part for storing and holding an electronic component; and

a second board which is electrically connected to the electronic component held to the first board, thereby being united with the first board.

4. The integral type electronic component according to claim 3, wherein the component storage part has a side wall for shielding light of a light-emitting element when the electronic component is the light-emitting element.

5. The integral type electronic component according to claim 3, wherein the first board is formed of any one of glass, ceramic and an organic resin.

6. The integral type electronic component according to claim 4, wherein the first board is formed of any one of glass, ceramic and an organic resin.

7. The integral type electronic component according to claim 3, wherein the electronic component is held to the component storage part with a photo-curing type insulating resin.

8. The integral type electronic component according to claim 4, wherein the electronic component is held to the component storage part with a photo-curing type insulating resin.

9. The integral type electronic component according to claim 5, wherein the electronic component is held to the component storage part with a photo-curing type insulating resin.

10. The integral type electronic component according to claim 6, wherein the electronic component is held to the component storage part with a photo-curing type insulating resin.